TEXAS INSTRUMENTS
DRV5023
JAJSBZ9G – MAY 2014 – REVISED SEPTEMBER 2016

DRV5023デジタル・スイッチ・ホール効果センサ

1 特長

- デジタル・ユニポーラスイッチ・ホール・センサ
- 優れた温度安定性
  - 温度範囲の全体で感度±10%
- 複数の感度オプション(B_{OP} / B_{RP})
  - 3.5 / 2mT (FA、図 24を参照)
  - 6.9 / 3.2mT (AJ、図 24を参照)
  - 14.5 / 6mT (BI、図 24を参照)
- 広い範囲の電圧をサポート
  - 2.5～38V
  - 外部レギュレータ不要
- 広い範囲の温度で動作
  - T_A = –40～125℃ (Q、図 24を参照)
- オープン・ドレイン出力(30mAシンク)
- 高速な電源オン時間: 35µs
- 小さなパッケージと占有面積
  - 表面実装の3ピンSOT-23 (DBZ)
    - 2.92mm×2.37mm
  - スルーホールの3ピンTO-92 (LPG)
    - 4.00mm×3.15mm
- 保護機能
  - 逆電圧保護(最大-22V)
  - 40Vまでの負荷ダンプをサポート
  - 出力短絡保護
  - 出力電流制限

2 アプリケーション

- ドッキング検出
- ドアの開閉検出
- 近接センシング
- バルブの位置決め
- パルスのカウント

3 概要

DRV5023デバイスはチョッパ安定化されたホール効果センサで、温度範囲全体にわたって優れた感度の安定性を持つ磁気センシング・ソリューションを提供し、保護機能が内蔵されています。

周囲の磁束密度がB_{OP}スレッショルドを超えると、DRV5023のオープン・ドレイン出力がLOWに変化します。磁場がB_{RP}未満に低下するまで出力はLOWに維持され、その後で出力がハイ・インピーダンスになります。出力電流のシンク能力は30mAです。2.5～38Vまでの広い範囲の電圧で動作し、-22Vまでの逆電圧から保護されるため、広範な産業用アプリケーションに適したデバイスです。

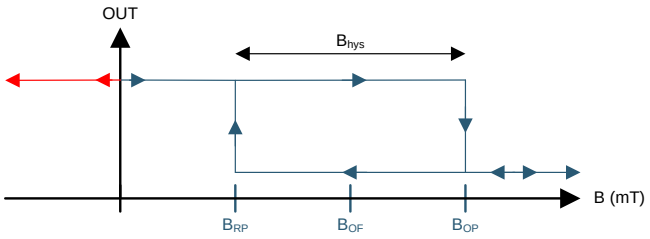
逆電圧の状態、負荷ダンプ、および出力短絡や過電流に対して、内部的な保護機能が搭載されています。

製品情報(1)

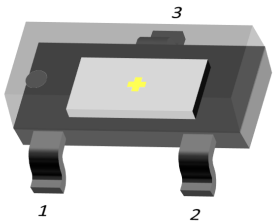
型番	パッケージ	本体サイズ(公称)
DRV5023	SOT-23 (3)	2.92mm×1.30mm
	TO-92 (3)	4.00mm×3.15mm

(1) 提供されているすべてのパッケージについては、巻末の注文情報を参照してください。

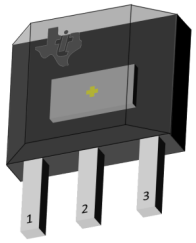
出力状態



SOT-23



TO-92



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4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Revision F (May 2016) から **Revision G** に変更 **Page**

- Changed the power-on time for the FA version in the *Electrical Characteristics* table ... 6
- Added the *Layout* section ... 19
- 追加「*ドキュメントの更新通知を受け取る方法*」セクション ... 21

Revision E (February 2016) から **Revision F** に変更 **Page**

- Revised preliminary limits for the FA version ... 6

Revision D (December 2015) から **Revision E** に変更 **Page**

- FAデバイス・オプション 追加 ... 1
- Added the typical bandwidth value to the *Magnetic Characteristics* table ... 6

Revision C (May 2015) から **Revision D** に変更 **Page**

- SOT-23パッケージの本体サイズを訂正し、SIPパッケージ名をTO-92に訂正 ... 1
- Added B_{MAX} to *Absolute Maximum Ratings* ... 5
- Removed table note from junction temperature ... 5
- パッケージのテープ&リールに関するMとブランクのオプションを更新 ... 20
- コミュニティ・リソースを追加 ... 21

Revision B (September 2014) から **Revision C** に変更 **Page**

- デバイスのステータスを量産データに更新 ... 1

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Revision A (August 2014) から Revision B に変更 **Page**

- 高感度オプションを+6.9 / +3.2mT (AJ)および+14.5 / +6mT (BI)へ更新 1
- Added typical rise and fall time and removed maximum value 6
- Updated the device values and typical values in *Magnetic Characteristics* 6
- Updated all *Typical Characteristics* graphs 7
- Updated Equation 4 17
- 図 24を更新 20

2014年5月発行のものから更新 **Page**

- 高感度オプションを+6.9 / +2.3mT (AJ)から+6.9 / +3.3mT (AJ)へ 変更 1
- Changed the maximum T_J value from 175°C to 150°C 5
- Changed MIN value for I_{OCP} from 20 to 15 6
- Changed Max value for I_{OCP} from 40 to 45 6
- Updated *Magnetic Characteristics* table. 6

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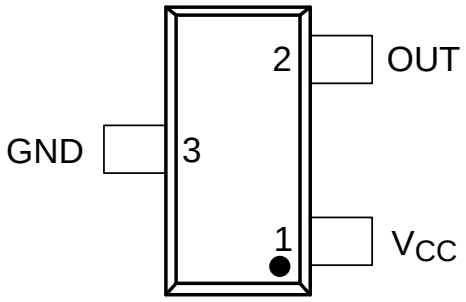
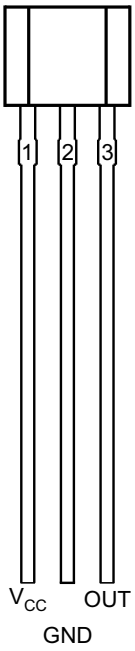
5 Pin Configuration and Functions

For additional configuration information, see デバイスのマーキング and メカニカル、パッケージ、および注文情報.

DBZ Package
3-Pin SOT-23
Top View



LPG Package
3-Pin TO-92
Top View



Pin Functions

PIN			TYPE	DESCRIPTION
NAME	DBZ	LPG		
GND	3	2	GND	Ground pin
OUT	2	3	Output	Hall sensor open-drain output. The open drain requires a resistor pullup.
V_{CC}	1	1	Power	2.5 to 38 V power supply. Bypass this pin to the GND pin with a 0.01-μF (minimum) ceramic capacitor rated for V_{CC}.

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6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Power supply voltage	V_{CC}	–22(2)	40	V
	Voltage ramp rate (V_{CC}), V_{CC} < 5 V	Unlimited		V/µs
	Voltage ramp rate (V_{CC}), V_{CC} > 5 V	0	2	
Output pin voltage		–0.5	40	V
Output pin reverse current during reverse supply condition		0	100	mA
Magnetic flux density, B_{MAX}		Unlimited		
Operating junction temperature, T_J		–40	150	°C
Storage temperature, T_{stg}		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) Ensured by design. Only tested to –20 V.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±2500	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Power supply voltage	2.5	38	V
V_O	Output pin voltage (OUT)	0	38	V
I_{SINK}	Output pin current sink (OUT)(1)	0	30	mA
T_A	Operating ambient temperature	–40	125	°C

(1) Power dissipation and thermal limits must be observed.

6.4 Thermal Information

THERMAL METRIC(1)		DRV5023		UNIT
		DBZ (SOT-23)	LPG (TO-92)	
		3 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	333.2	180	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	99.9	98.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	66.9	154.9	°C/W
ψ_{JT}	Junction-to-top characterization parameter	4.9	40	°C/W
ψ_{JB}	Junction-to-board characterization parameter	65.2	154.9	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

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6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLIES (V_{CC})						
V_{CC}	V_{CC} operating voltage		2.5		38	V
I_{CC}	Operating supply current	V_{CC} = 2.5 to 38 V, T_A = 25°C		2.7		mA
		V_{CC} = 2.5 to 38 V, T_A = 125°C		3	3.5	
t_{on}	Power-on time	AJ, BI versions		35	50	µs
		FA version		35	70	
OPEN DRAIN OUTPUT (OUT)						
$r_{DS(on)}$	FET on-resistance	V_{CC} = 3.3 V, I_O = 10 mA, T_A = 25°C		22		Ω
		V_{CC} = 3.3 V, I_O = 10 mA, T_A = 125°C		36	50	
$I_{lkg(off)}$	Off-state leakage current	Output Hi-Z			1	µA
PROTECTION CIRCUITS						
V_{CCR}	Reverse supply voltage		–22			V
I_{OCP}	Overcurrent protection level	OUT shorted V_{CC}	15	30	45	mA

6.6 Switching Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
OPEN DRAIN OUTPUT (OUT)						
t_d	Output delay time	B = B_{RP} – 10 mT to B_{OP} + 10 mT in 1 µs		13	25	µs
t_r	Output rise time (10% to 90%)	R1 = 1 kΩ, C_O = 50 pF, V_{CC} = 3.3 V		200		ns
t_f	Output fall time (90% to 10%)	R1 = 1 kΩ, C_O = 50 pF, V_{CC} = 3.3 V		31		ns

6.7 Magnetic Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT(1)
f_{BW}	Bandwidth(2)		20	30		kHz
DRV5023FA: 3.5 / 2 mT						
B_{OP}	Operate point (see Figure 12)	T_A = –40°C to 125°C	1.8	3.5	6.8	mT
B_{RP}	Release point (see Figure 12)		0.5	2	4.2	mT
B_{hys}	Hysteresis; B_{hys}= (B_{OP} – B_{RP})			1.5		mT
B_O	Magnetic offset, B_O = (B_{OP} + B_{RP}) / 2			2.8		mT
DRV5023AJ: 6.9 / 3.2 mT						
B_{OP}	Operate point (see Figure 12)	T_A = –40°C to 125°C	3	6.9	12	mT
B_{RP}	Release point (see Figure 12)		1	3.2	5	mT
B_{hys}	Hysteresis; B_{hys}= (B_{OP} – B_{RP})			3.7		mT
B_O	Magnetic offset, B_O = (B_{OP} + B_{RP}) / 2			5		mT
DRV5023BI: 14.5 / 6 mT						
B_{OP}	Operate point (see Figure 12)	T_A = –40°C to 125°C	6	14.5	24	mT
B_{RP}	Release point (see Figure 12)		3	6	9	mT
B_{hys}	Hysteresis; B_{hys} = (B_{OP} – B_{RP})(3)			8.5		mT
B_O	Magnetic offset, B_O = (B_{OP} + B_{RP}) / 2			10.3		mT

(1) 1 mT = 10 Gauss
(2) Bandwidth describes the fastest changing magnetic field that can be detected and translated to the output.
(3) $|B_{OP}|$ is always greater than $|B_{RP}|$.

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6.8 Typical Characteristics

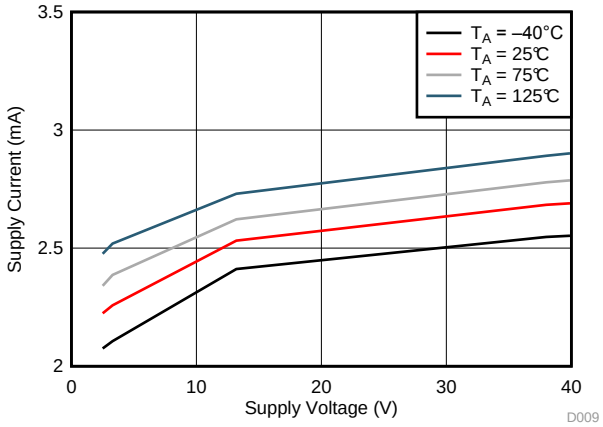

Figure 1. I_{CC} vs V_{CC}

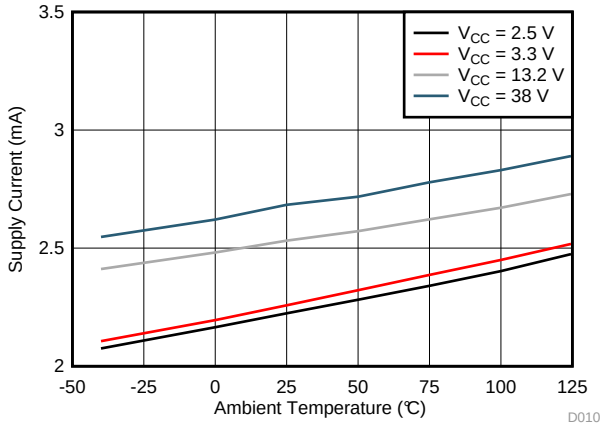

Figure 2. I_{CC} vs Temperature

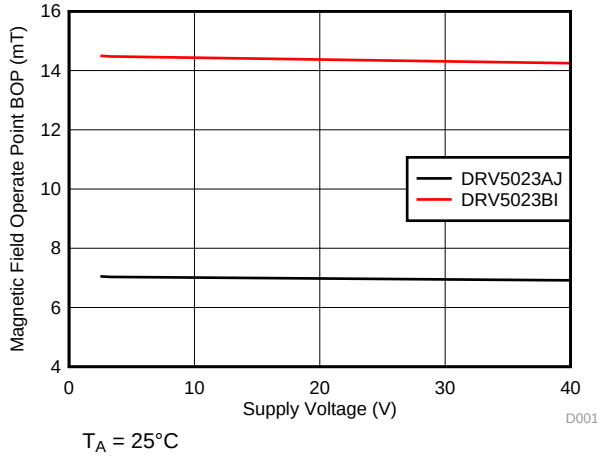

Figure 3. B_{OP} vs V_{CC}

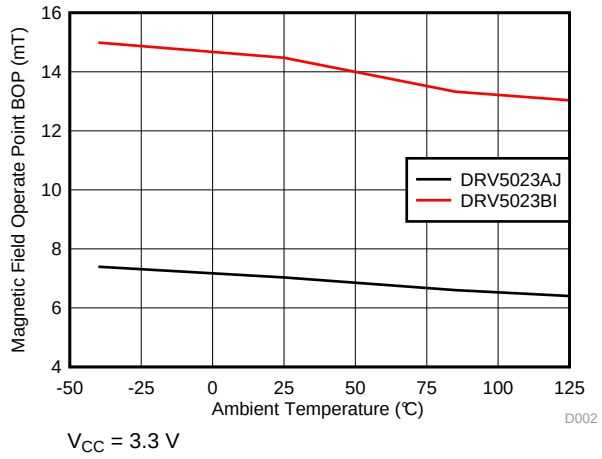

Figure 4. B_{OP} vs Temperature

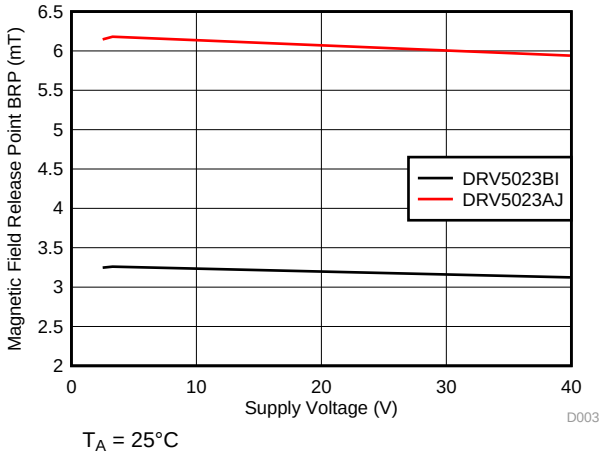

Figure 5. B_{RP} vs V_{CC}

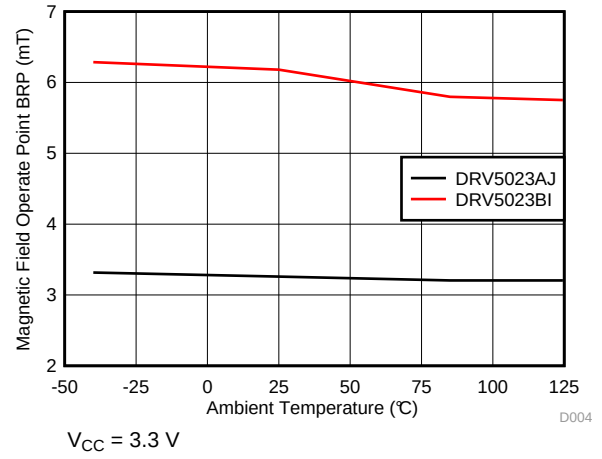

Figure 6. B_{RP} vs Temperature

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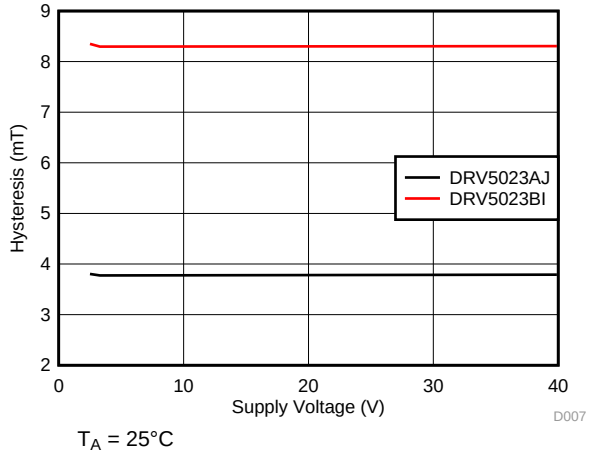
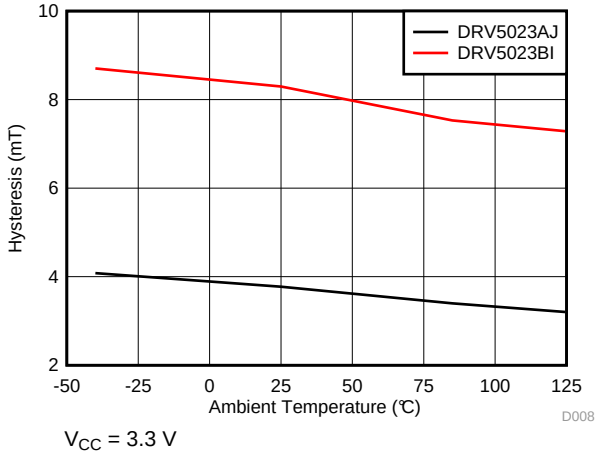
Typical Characteristics (continued)



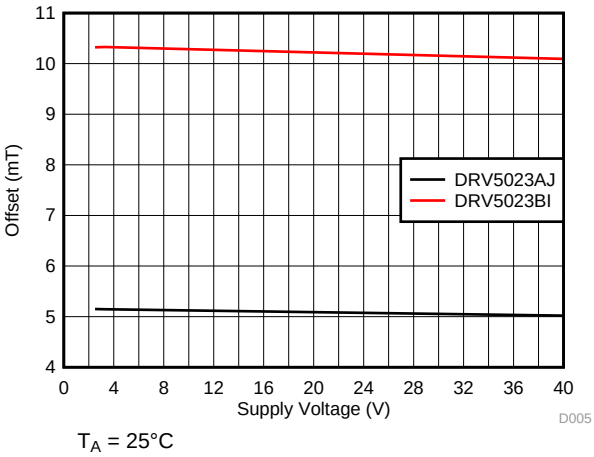
T_A = 25°C

Figure 7. Hysteresis vs V_{CC}



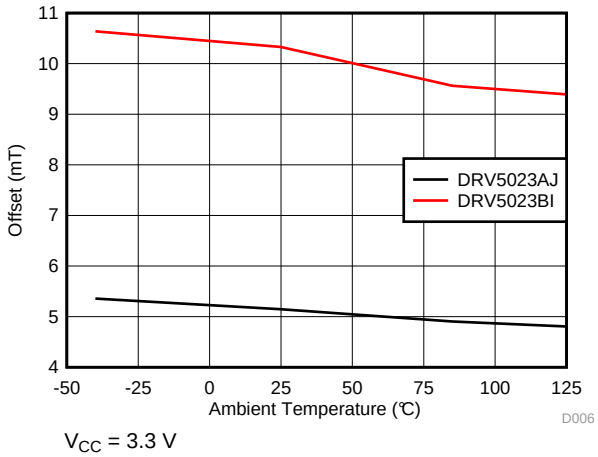
V_{CC} = 3.3 V

Figure 8. Hysteresis vs Temperature



T_A = 25°C

Figure 9. Offset vs V_{CC}



V_{CC} = 3.3 V

Figure 10. Offset vs Temperature

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7 Detailed Description

7.1 Overview

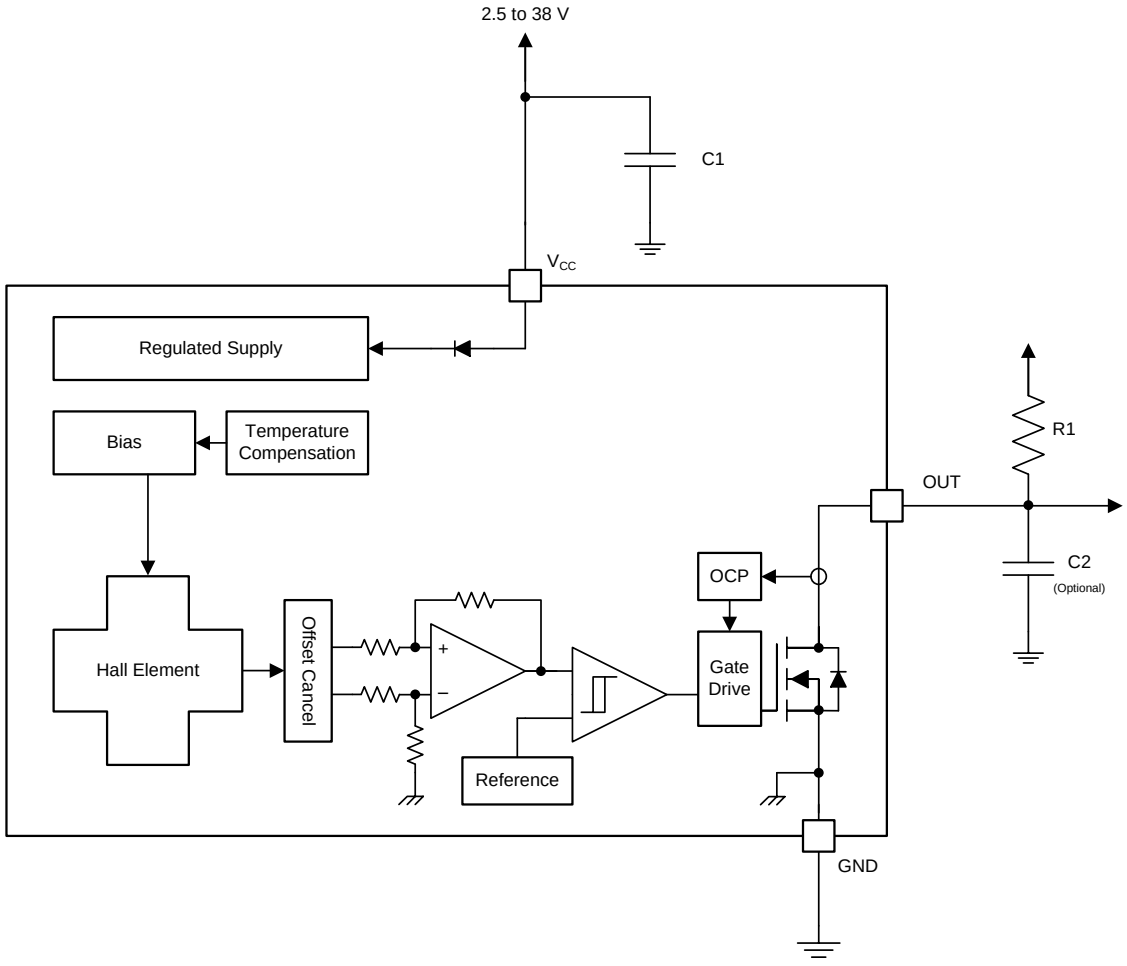
The DRV5023 device is a chopper-stabilized Hall sensor with a digital output for magnetic sensing applications. The DRV5023 device can be powered with a supply voltage between 2.5 and 38 V, and will survive –22 V reverse-battery conditions. The DRV5023 device does not operate when –22 to 2.4 V is applied to the V_{CC} pin (with respect to GND pin). In addition, the device can withstand supply voltages up to 40 V for transient durations.

The field polarity is defined as follows: a south pole near the marked side of the package is a positive magnetic field. A north pole near the marked side of the package is a negative magnetic field.

The output state is dependent on the magnetic field perpendicular to the package. A strong south pole near the marked side of the package causes the output to pull low (operate point, BOP), and a weak south pole causes the output to release (release point, BRP). Hysteresis is included in between the operate point and the release point therefore magnetic-field noise does not accidentally trip the output.

An external pullup resistor is required on the OUT pin. The OUT pin can be pulled up to V_{CC}, or to a different voltage supply. This allows for easier interfacing with controller circuits.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Field Direction Definition

A positive magnetic field is defined as a south pole near the marked side of the package as shown in Figure 11.

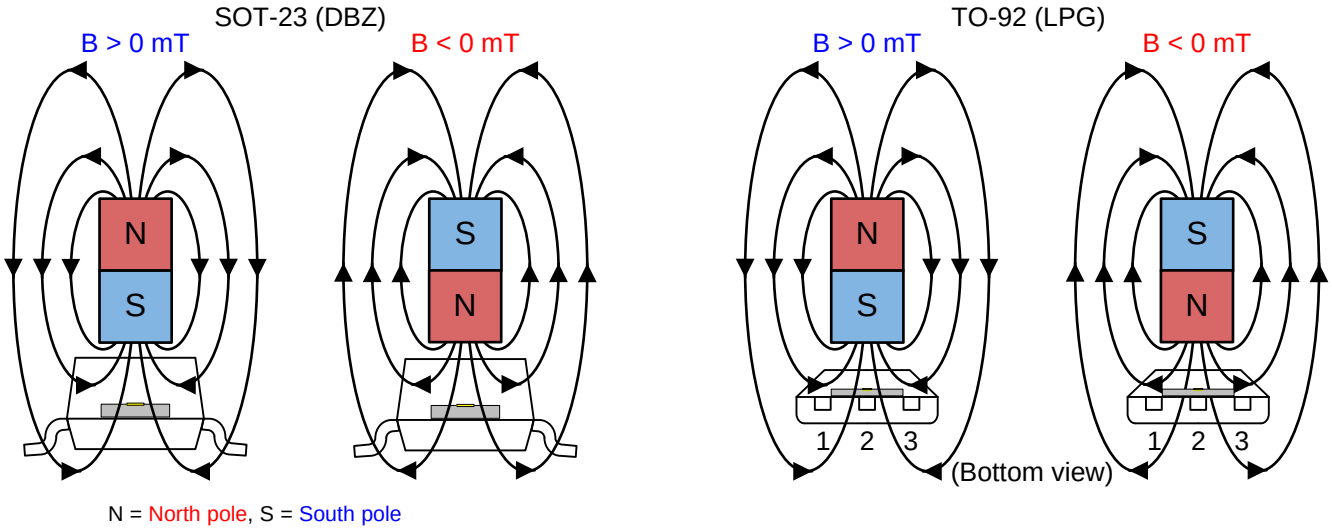


Figure 11. Field Direction Definition

7.3.2 Device Output

If the device is powered on with a magnetic field strength between B_{RP} and B_{OP}, then the device output is indeterminate and can either be Hi-Z or Low. For the FA, AJ, and BI device versions, if the field strength is greater than B_{OP}, then the output is pulled low; if the field strength is less than B_{RP}, then the output is released. For the FI device version, if the field strength is greater than B_{OP}, then the output is Hi-Z; if the field strength is less than B_{RP}, then the output is pulled Low.

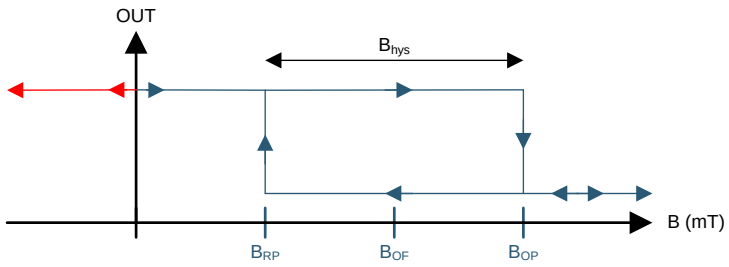


Figure 12. Output State

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Feature Description (continued)

7.3.3 Power-On Time

After applying V_{CC} to the DRV5023 device, t_{on} must elapse before the OUT pin is valid. During the power-up sequence, the output is Hi-Z. A pulse as shown in Figure 13 and Figure 14 occurs at the end of t_{on}. This pulse can allow the host processor to determine when the DRV5023 output is valid after startup. In Case 1 (Figure 13) and Case 2 (Figure 14), the output is defined assuming a constant magnetic field B > B_{OP} and B < B_{RP}.

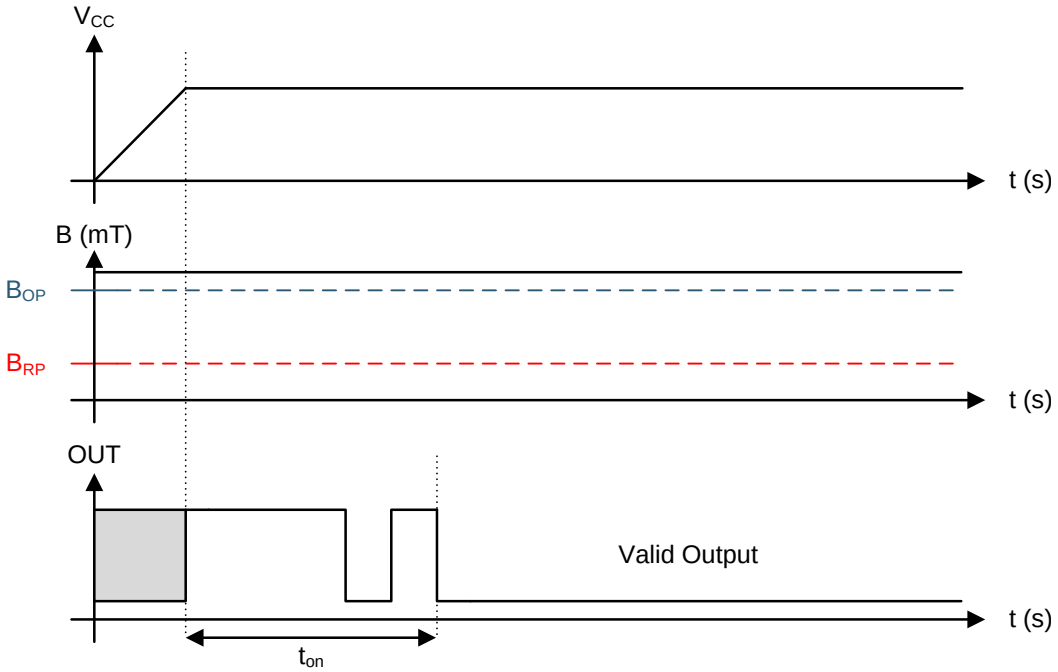

Figure 13. Case 1: Power On When B > B_{OP}

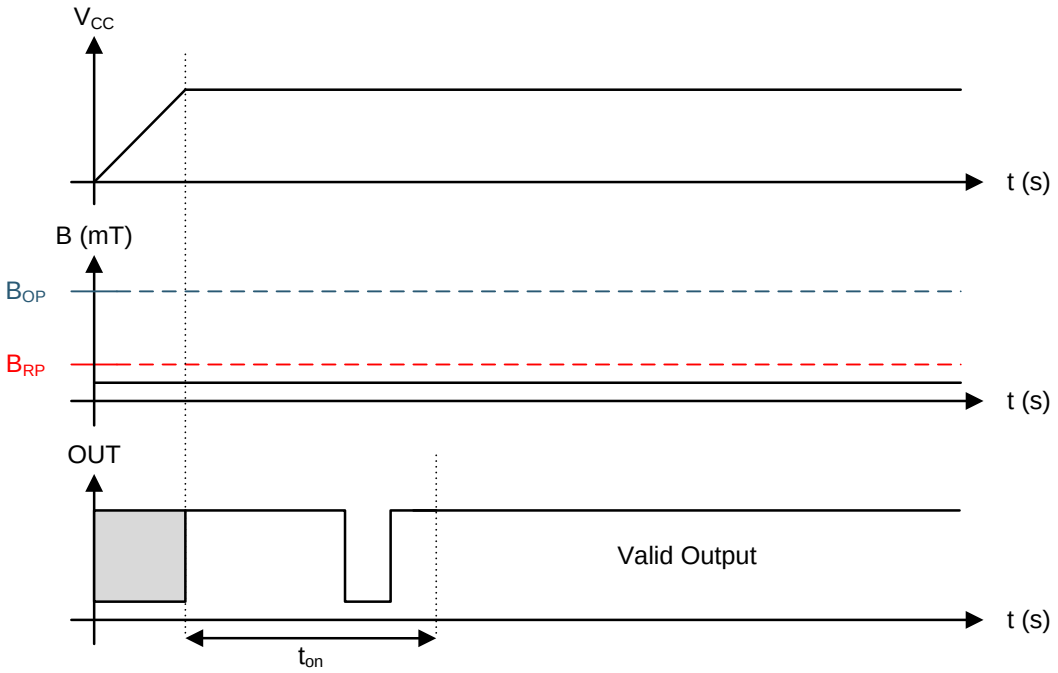

Figure 14. Case 2: Power On When B < B_{RP}

Feature Description (continued)

If the device is powered on with the magnetic field strength B_{RP} < B < B_{OP}, then the device output is indeterminate and can either be Hi-Z or pulled low. During the power-up sequence, the output is held Hi-Z until t_{on} has elapsed. At the end of t_{on}, a pulse is given on the OUT pin to indicate that t_{on} has elapsed. After t_{on}, if the magnetic field changes such that B_{OP} < B, the output is released. Case 3 (Figure 15) and Case 4 (Figure 16) show examples of this behavior.

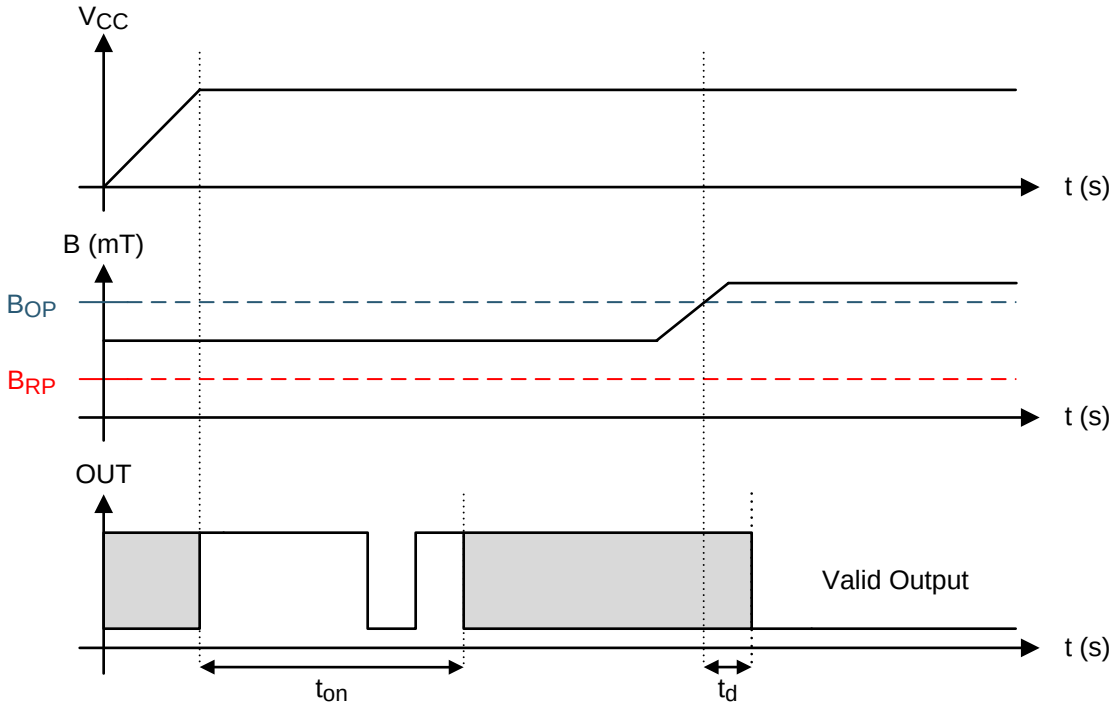

Figure 15. Case 3: Power On When B_{RP} < B < B_{OP}, Followed by B > B_{OP}

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Feature Description (continued)

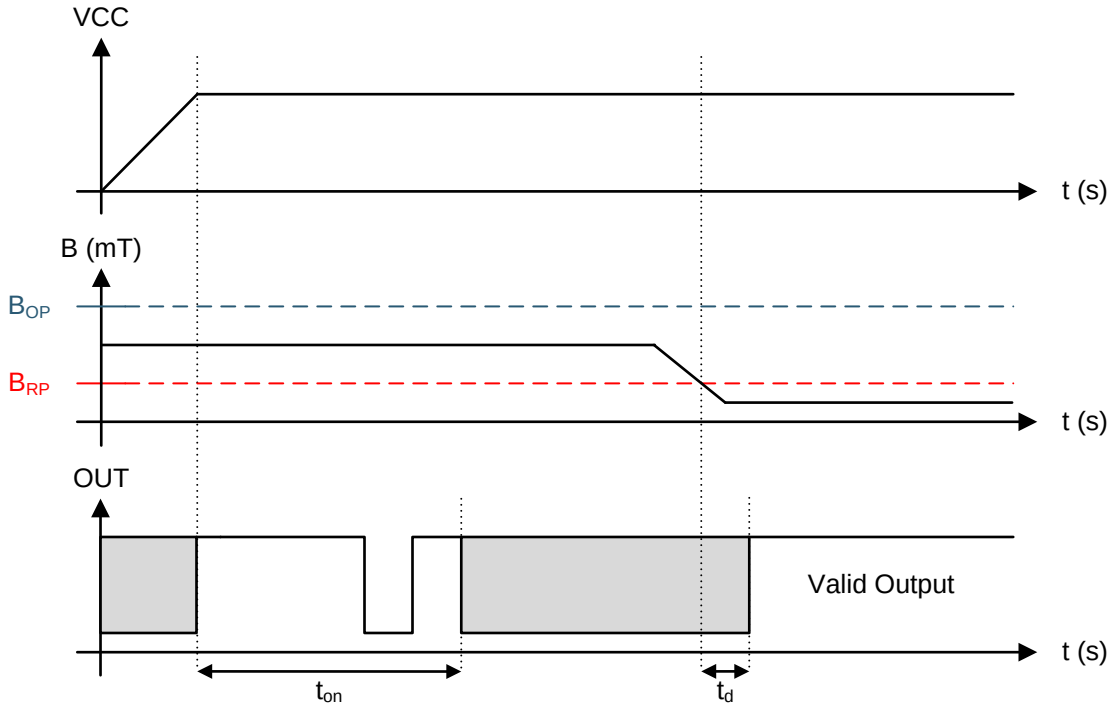

Figure 16. Case 4: Power On When B_{RP} < B < B_{OP}, Followed by B < B_{RP}

Feature Description (continued)

7.3.4 Output Stage

The DRV5023 output stage uses an open-drain NMOS, and it is rated to sink up to 30 mA of current. For proper operation, calculate the value of the pullup resistor R1 using Equation 1.

$$\frac{V_{ref}\,max}{30\ mA} \le R1 \le \frac{V_{ref}\,min}{100\ \mu A} \quad (1)$$

The size of R1 is a tradeoff between the OUT rise time and the current when OUT is pulled low. A lower current is generally better, however faster transitions and bandwidth require a smaller resistor for faster switching.

In addition, ensure that the value of R1 > 500 Ω to ensure the output driver can pull the OUT pin close to GND.

NOTE

V_{ref} is not restricted to V_{CC}. The allowable voltage range of this pin is specified in the *Absolute Maximum Ratings*.

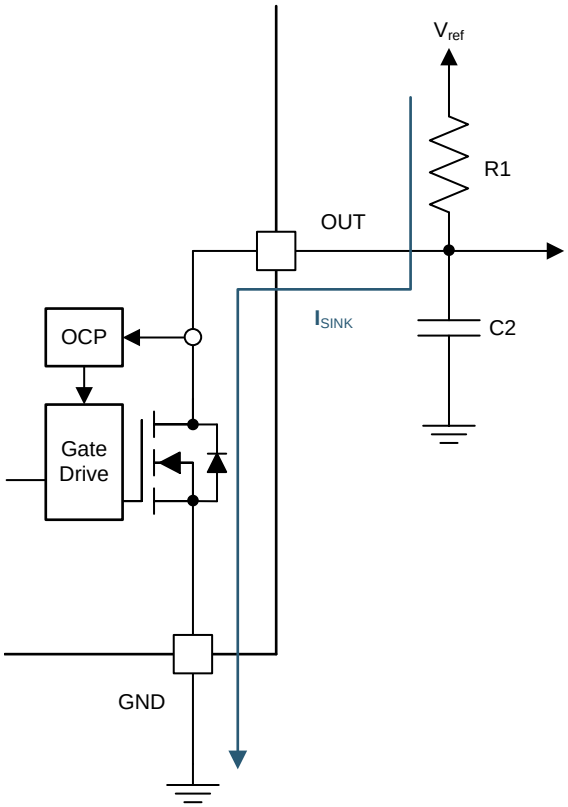

Figure 17.

Select a value for C2 based on the system bandwidth specifications as shown in Equation 2.

$$2 \times f_{BW}\ (Hz) < \frac{1}{2\pi \times R1 \times C2} \quad (2)$$

Most applications do no require this C2 filtering capacitor.

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Feature Description (continued)

7.3.5 Protection Circuits

The DRV5023 device is fully protected against overcurrent and reverse-supply conditions.

7.3.5.1 Overcurrent Protection (OCP)

An analog current-limit circuit limits the current through the FET. The driver current is clamped to I_{OCP}. During this clamping, the $r_{DS(on)}$ of the output FET is increased from the nominal value.

7.3.5.2 Load Dump Protection

The DRV5023 device operates at DC V_{CC} conditions up to 38 V nominally, and can additionally withstand V_{CC} = 40 V. No current-limiting series resistor is required for this protection.

7.3.5.3 Reverse Supply Protection

The DRV5023 device is protected in the event that the V_{CC} pin and the GND pin are reversed (up to –22 V).

NOTE

In a reverse supply condition, the OUT pin reverse-current must not exceed the ratings specified in the *Absolute Maximum Ratings*.

Table 1.

FAULT	CONDITION	DEVICE	DESCRIPTION	RECOVERY
FET overload (OCP)	$I_{SINK} \geq I_{OCP}$	Operating	Output current is clamped to I_{OCP}	$I_O < I_{OCP}$
Load dump	38 V < V_{CC} < 40 V	Operating	Device will operate for a transient duration	$V_{CC} \leq$ 38 V
Reverse supply	–22 V < V_{CC} < 0 V	Disabled	Device will survive this condition	$V_{CC} \geq$ 2.5 V

7.4 Device Functional Modes

The DRV5023 device is active only when V_{CC} is between 2.5 and 38 V.

When a reverse supply condition exists, the device is inactive.

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8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The DRV5023 device is used in magnetic-field sensing applications.

8.2 Typical Applications

8.2.1 Standard Circuit

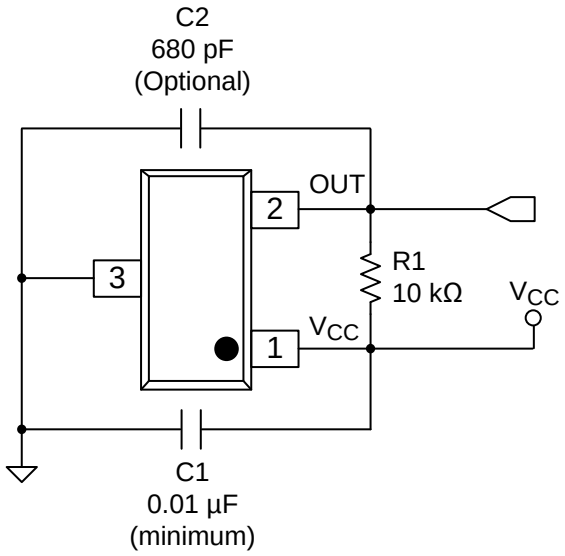

Figure 18. Typical Application Circuit

8.2.1.1 Design Requirements

For this design example, use the parameters listed in Table 2 as the input parameters.

Table 2. Design Parameters

DESIGN PARAMETER	REFERENCE	EXAMPLE VALUE
Supply voltage	V_{CC}	3.2 to 3.4 V
System bandwidth	f_{BW}	10 kHz

8.2.1.2 Detailed Design Procedure

Table 3. External Components

COMPONENT	PIN 1	PIN 2	RECOMMENDED
C1	V_{CC}	GND	A 0.01-µF (minimum) ceramic capacitor rated for V_{CC}
C2	OUT	GND	**Optional**: Place a ceramic capacitor to GND
R1	OUT	REF(1)	Requires a resistor pullup

(1) REF is not a pin on the DRV5023 device, but a REF supply-voltage pullup is required for the OUT pin; the OUT pin may be pulled up to V_{CC}.

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8.2.1.2.1 Configuration Example

In a 3.3-V system, 3.2 V ≤ V_{ref} ≤ 3.4 V. Use Equation 3 to calculate the allowable range for R1.

$$\frac{V_{ref}\,max}{30\ mA} \leq R1 \leq \frac{V_{ref}\,min}{100\ \mu A} \tag{3}$$

For this design example, use Equation 4 to calculate the allowable range of R1.

$$\frac{3.4\ V}{30\ mA} \leq R1 \leq \frac{3.2\ V}{100\ \mu A} \tag{4}$$

Therefore:

$$113\ \Omega \leq R1 \leq 32\ k\Omega \tag{5}$$

After finding the allowable range of R1 (Equation 5), select a value between 500 Ω and 32 kΩ for R1.

Assuming a system bandwidth of 10 kHz, use Equation 6 to calculate the value of C2.

$$2 \times f_{BW}\ (Hz) < \frac{1}{2\pi \times R1 \times C2} \tag{6}$$

For this design example, use Equation 7 to calculate the value of C2.

$$2 \times 10\ kHz < \frac{1}{2\pi \times R1 \times C2} \tag{7}$$

An R1 value of 10 kΩ and a C2 value less than 820 pF satisfy the requirement for a 10-kHz system bandwidth.

A selection of R1 = 10 kΩ and C2 = 680 pF would cause a low-pass filter with a corner frequency of 23.4 kHz.

8.2.1.3 Application Curves

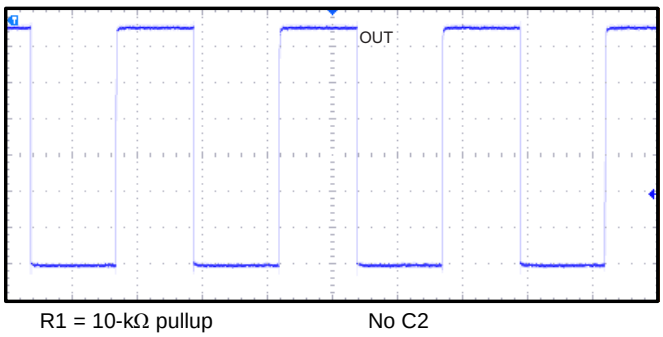

Figure 19. 10-kHz Switching Magnetic Field

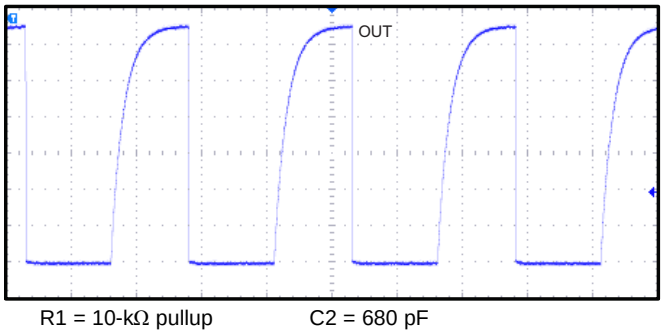

Figure 20. 10-kHz Switching Magnetic Field

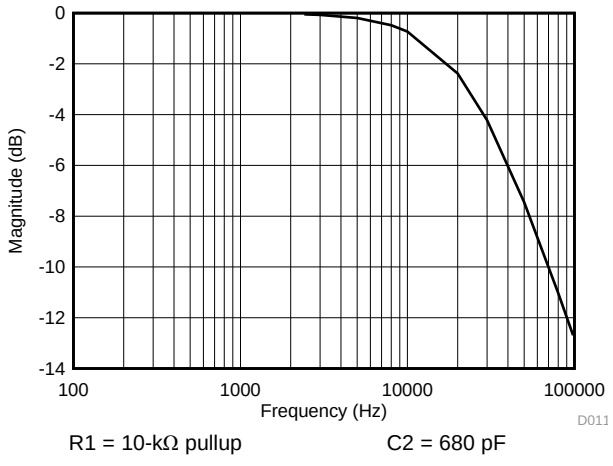

Figure 21. Low-Pass Filtering

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8.2.2 Alternative Two-Wire Application

For systems that require minimal wire count, the device output can be connected to V_{CC} through a resistor, and the total supplied current can be sensed near the controller.

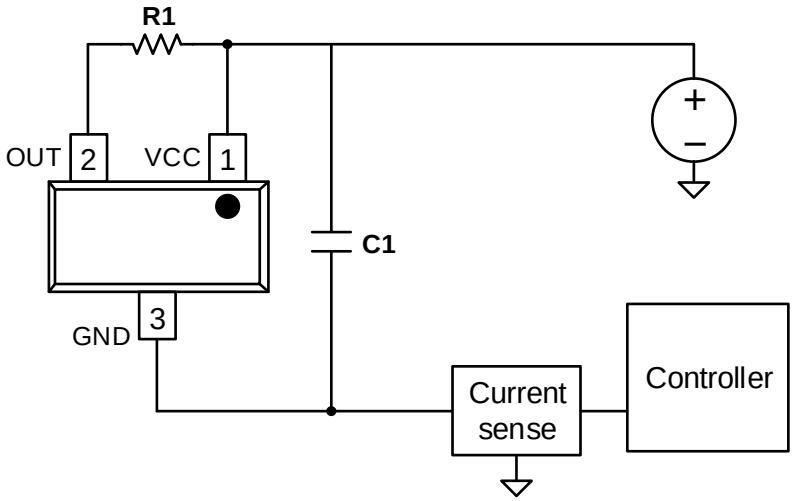

Figure 22. 2-Wire Application

Current can be sensed using a shunt resistor or other circuitry.

8.2.2.1 Design Requirements

Table 4 lists the related design parameters.

Table 4. Design Parameters

DESIGN PARAMETER	REFERENCE	EXAMPLE VALUE
Supply voltage	V_{CC}	12 V
OUT resistor	R1	1 kΩ
Bypass capacitor	C1	0.1 µF
Current when B < B_{RP}	$I_{RELEASE}$	About 3 mA
Current when B > B_{OP}	$I_{OPERATE}$	About 15 mA

8.2.2.2 Detailed Design Procedure

When the open-drain output of the device is high-impedance, current through the path equals the I_{CC} of the device (approximately 3 mA).

When the output pulls low, a parallel current path is added, equal to V_{CC} / (R1 + $r_{DS(on)}$). Using 12 V and 1 kΩ, the parallel current is approximately 12 mA, making the total current approximately 15 mA.

The local bypass capacitor C1 should be at least 0.1 µF, and a larger value if there is high inductance in the power line interconnect.

9 Power Supply Recommendations

The DRV5023 device is designed to operate from an input voltage supply (VM) range between 2.5 and 38 V. A 0.01-µF (minimum) ceramic capacitor rated for V_{CC} must be placed as close to the DRV5023 device as possible.

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10 Layout

10.1 Layout Guidelines

The bypass capacitor should be placed near the DRV5023 device for efficient power delivery with minimal inductance. The external pullup resistor should be placed near the microcontroller input to provide the most stable voltage at the input; alternatively, an integrated pullup resistor within the GPIO of the microcontroller can be used.

Generally, using PCB copper planes underneath the DRV5023 device has no effect on magnetic flux, and does not interfere with device performance. This is because copper is not a ferromagnetic material. However, If nearby system components contain iron or nickel, they may redirect magnetic flux in unpredictable ways.

10.2 Layout Example

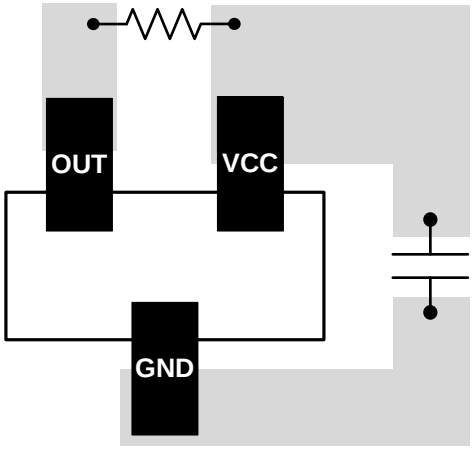

Figure 23. DRV5023 Layout Example

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11 デバイスおよびドキュメントのサポート

11.1 デバイス・サポート

11.1.1 デバイス名の見方

DRV5023のデバイス名の各部の読み方を図 24に示します。

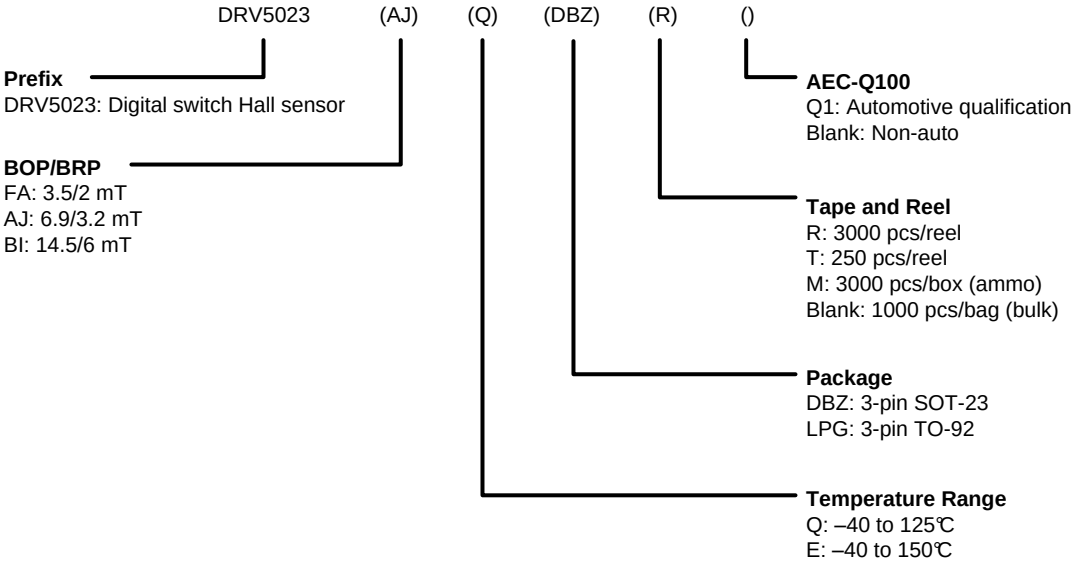

図 24. デバイス名の見方

11.1.2 デバイスのマーキング

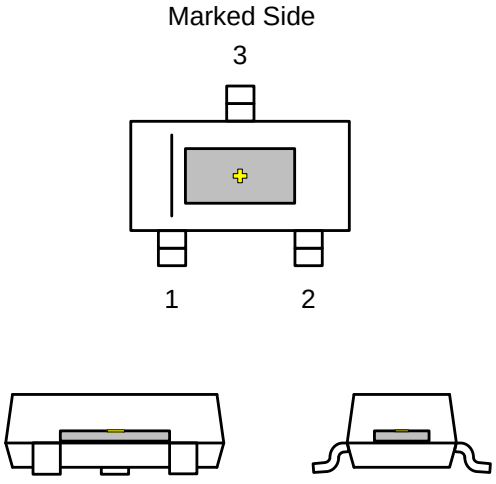

図 **25. SOT-23 (DBZ)**パッケージ

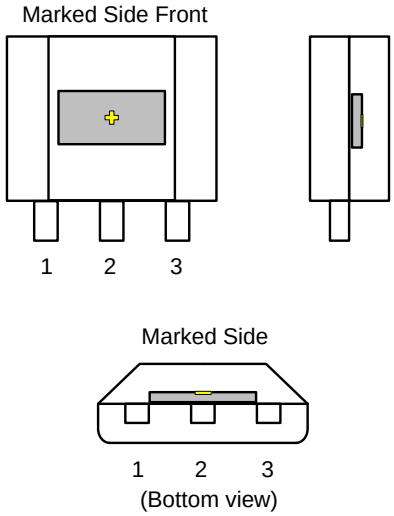

図 **26. TO-92 (LPG)**パッケージ

✚はホール効果センサを示します(実際の大きさに比例してはいません)。ホール素子はパッケージの中心に、許容誤差±100µmで配置されています。ホール素子の高さは、パッケージの底面から計測して、DBZパッケージでは0.7mm±50µm、LPGパッケージでは0.987mm±50µmです。

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11.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。これらの情報は、指定のデバイスに対して提供されている最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DRV5023AJQDBZR	Active	Production	SOT-23 (DBZ) | 3	3000 | LARGE T&R	Yes	NIPDAUAG | SN	Level-1-260C-UNLIM	-40 to 125	(+PLAJ, 1J22)
DRV5023AJQDBZR.A	Active	Production	SOT-23 (DBZ) | 3	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(+PLAJ, 1J22)
DRV5023AJQDBZT	Obsolete	Production	SOT-23 (DBZ) | 3	-	-	Call TI	Call TI	-40 to 125	(+PLAJ, 1J22)
DRV5023AJQLPG	Active	Production	TO-92 (LPG) | 3	1000 | BULK	Yes	SN	N/A for Pkg Type	-40 to 125	+PLAJ
DRV5023AJQLPG.A	Active	Production	TO-92 (LPG) | 3	1000 | BULK	Yes	SN	N/A for Pkg Type	-40 to 125	+PLAJ
DRV5023AJQLPGM	Active	Production	TO-92 (LPG) | 3	3000 | AMMO	Yes	SN	N/A for Pkg Type	-40 to 125	+PLAJ
DRV5023AJQLPGM.A	Active	Production	TO-92 (LPG) | 3	3000 | AMMO	Yes	SN	N/A for Pkg Type	-40 to 125	+PLAJ
DRV5023BIQDBZR	Active	Production	SOT-23 (DBZ) | 3	3000 | LARGE T&R	Yes	NIPDAUAG | SN	Level-1-260C-UNLIM	-40 to 125	(+PLBI, 1J32)
DRV5023BIQDBZR.A	Active	Production	SOT-23 (DBZ) | 3	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(+PLBI, 1J32)
DRV5023BIQDBZT	Obsolete	Production	SOT-23 (DBZ) | 3	-	-	Call TI	Call TI	-40 to 125	(+PLBI, 1J32)
DRV5023BIQLPG	Active	Production	TO-92 (LPG) | 3	1000 | BULK	Yes	SN	N/A for Pkg Type	-40 to 125	+PLBI
DRV5023BIQLPG.A	Active	Production	TO-92 (LPG) | 3	1000 | BULK	Yes	SN	N/A for Pkg Type	-40 to 125	+PLBI
DRV5023BIQLPGM	Active	Production	TO-92 (LPG) | 3	3000 | AMMO	Yes	SN	N/A for Pkg Type	-40 to 125	+PLBI
DRV5023BIQLPGM.A	Active	Production	TO-92 (LPG) | 3	3000 | AMMO	Yes	SN	N/A for Pkg Type	-40 to 125	+PLBI
DRV5023FAQDBZR	Active	Production	SOT-23 (DBZ) | 3	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(+PLFA, 1J42)
DRV5023FAQDBZR.A	Active	Production	SOT-23 (DBZ) | 3	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(+PLFA, 1J42)

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF DRV5023 :

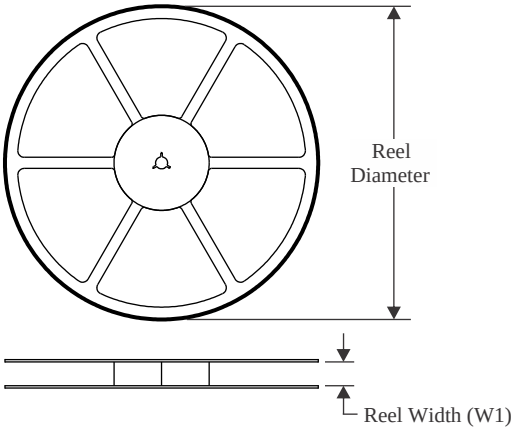
- Automotive : DRV5023-Q1

NOTE: Qualified Version Definitions:

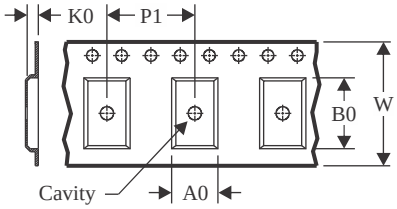
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

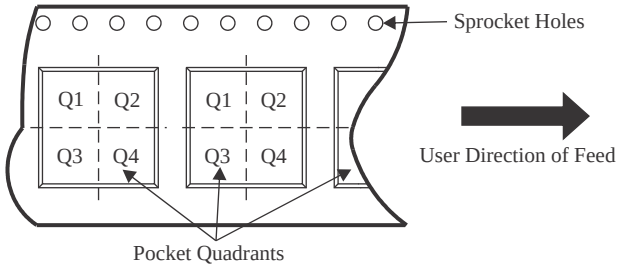


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

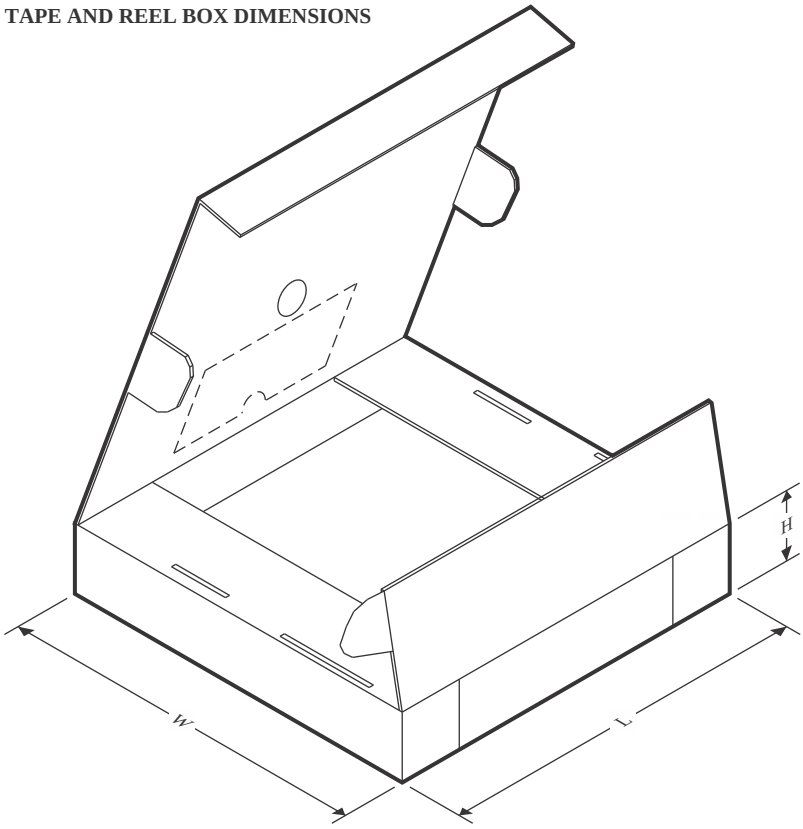
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV5023AJQDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.2	2.85	1.3	4.0	8.0	Q3
DRV5023BIQDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.2	2.85	1.3	4.0	8.0	Q3
DRV5023FAQDBZR	SOT-23	DBZ	3	3000	178.0	9.0	3.15	2.77	1.22	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

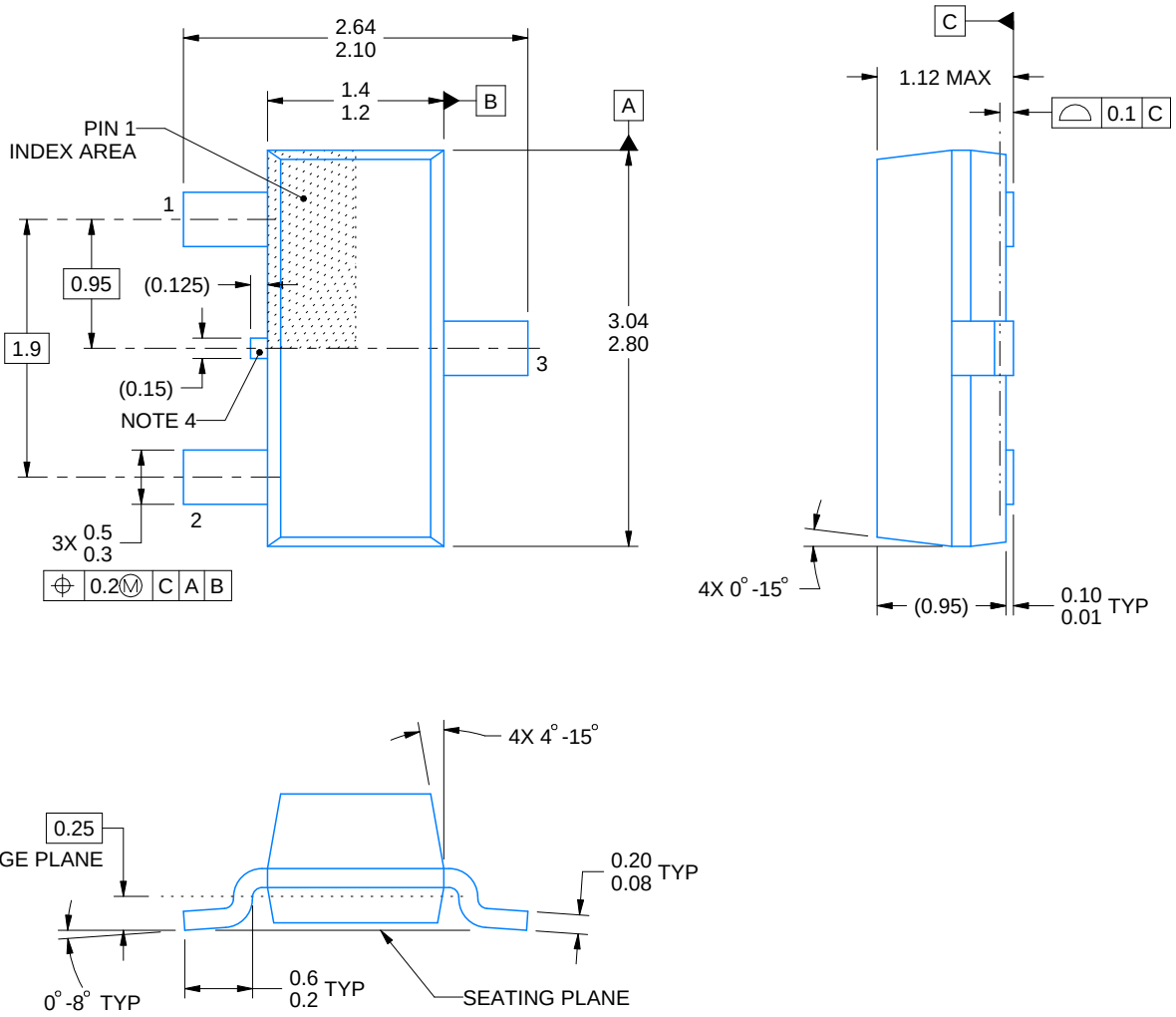
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV5023AJQDBZR	SOT-23	DBZ	3	3000	210.0	185.0	35.0
DRV5023BIQDBZR	SOT-23	DBZ	3	3000	210.0	185.0	35.0
DRV5023FAQDBZR	SOT-23	DBZ	3	3000	180.0	180.0	18.0

PACKAGE OUTLINE

DBZ0003A

SOT-23 - 1.12 mm max height

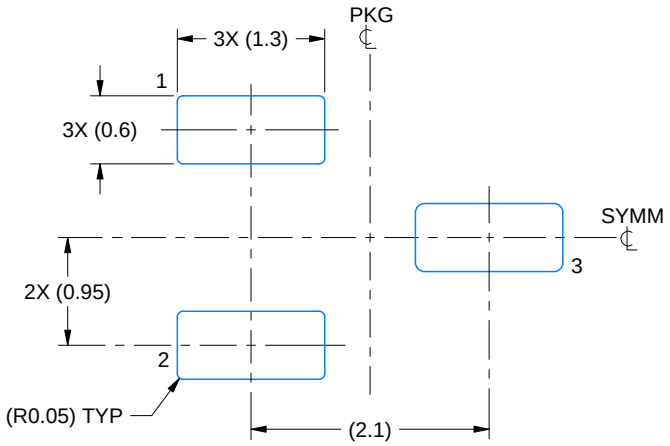
SMALL OUTLINE TRANSISTOR



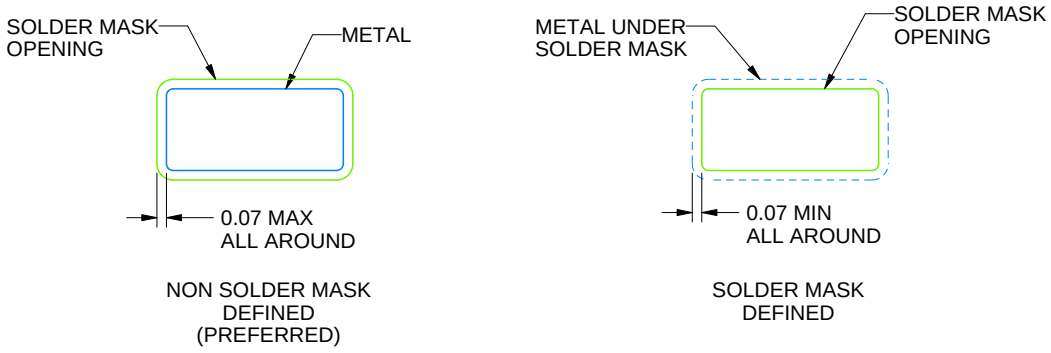
4214838/F 08/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-236, except minimum foot length.
4. Support pin may differ or may not be present.
5. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side



LAND PATTERN EXAMPLE
SCALE:15X



SOLDER MASK DETAILS

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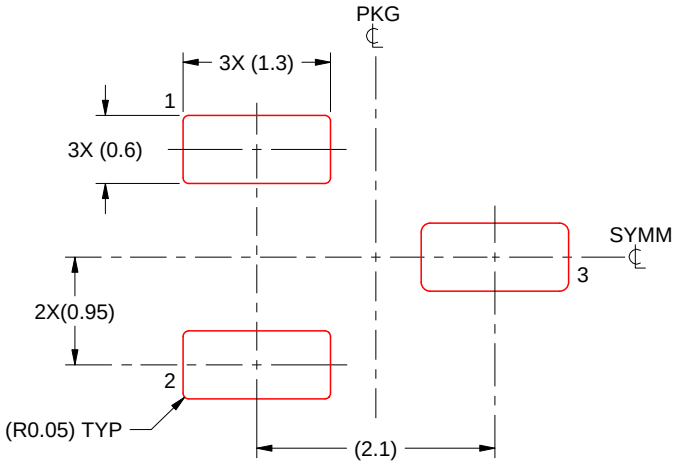
NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:15X

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NOTES: (continued)

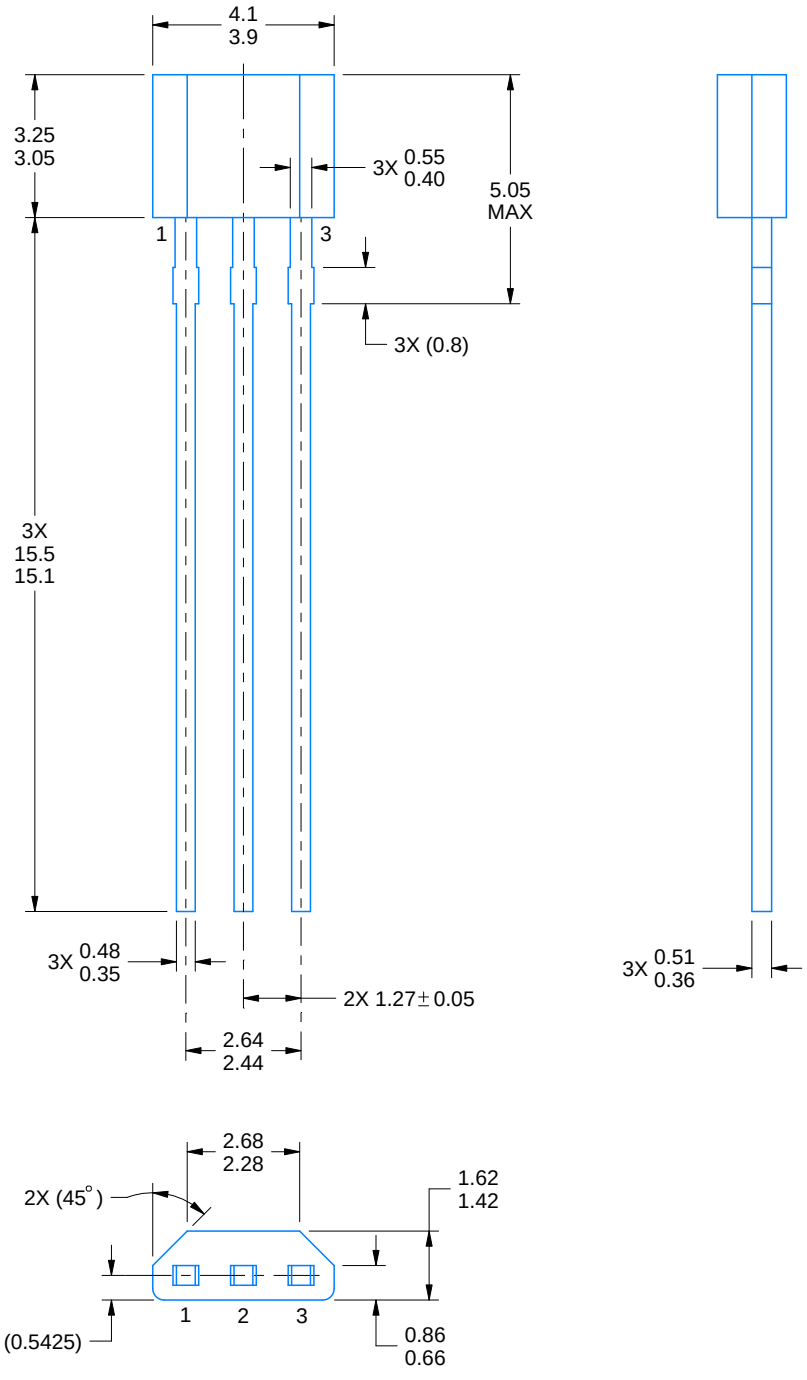
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

LPG0003A

TO-92 - 5.05 mm max height

TRANSISTOR OUTLINE



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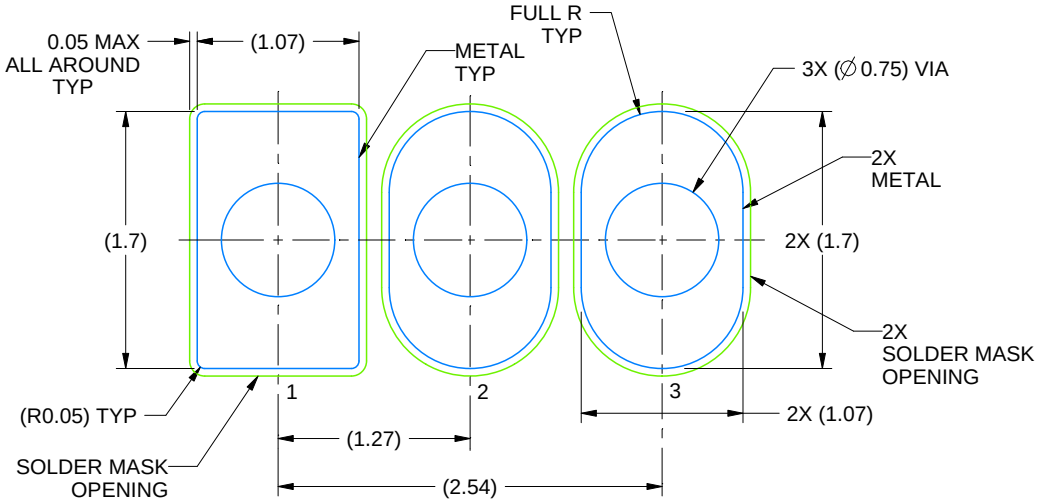
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE:20X

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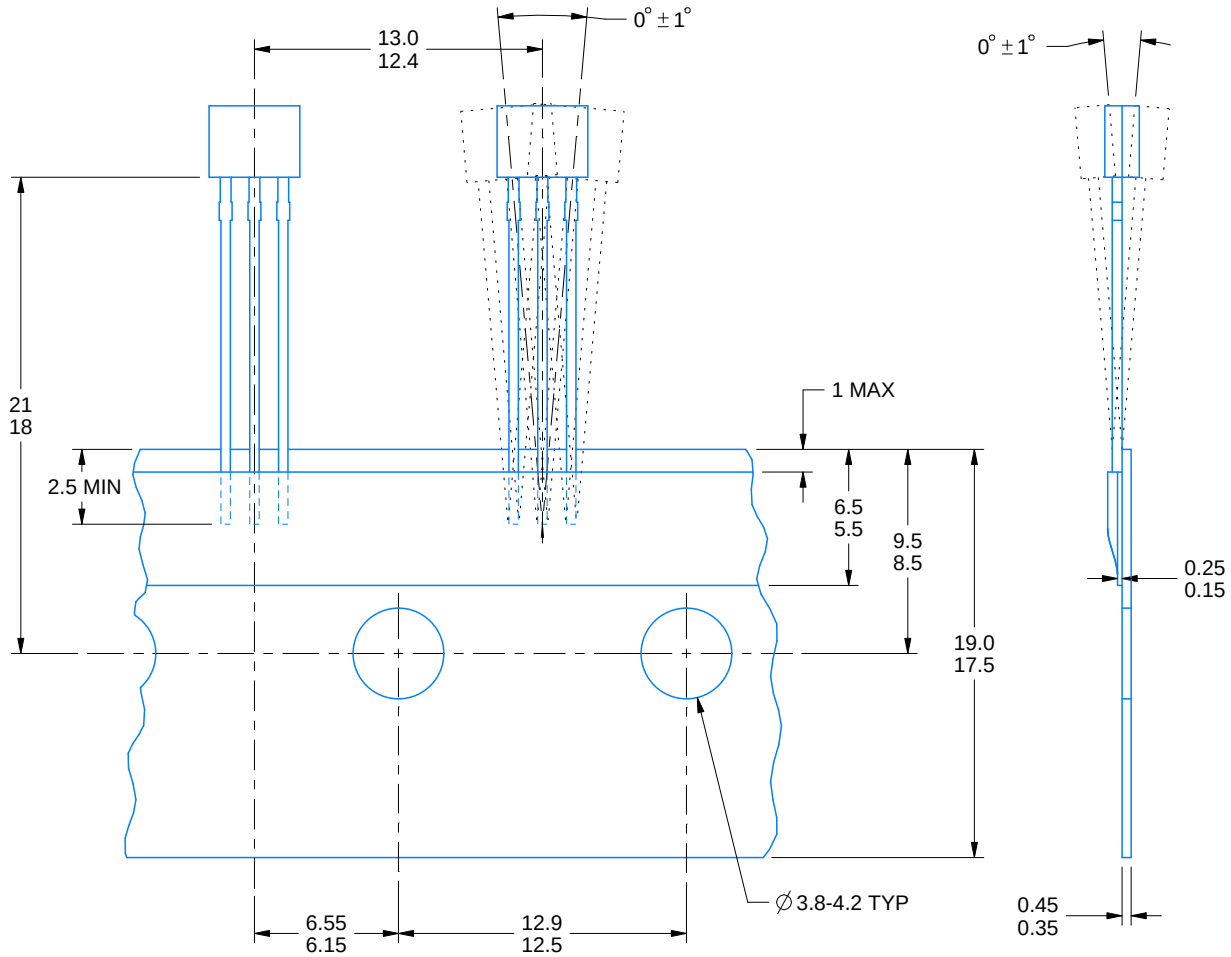
LPG0003A

TO-92 - 5.05 mm max height

TRANSISTOR OUTLINE



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